We periodically issue press releases and otherwise publicly distribute financial information about our company. This information includes filings that we make with the United States Securities and Exchange Commission. For the convenience of investors, we are providing access to this previously distributed information for reference purposes only. All of this information speaks solely as of the date of its original issuance and contains statements that can become outdated. These statements concern matters including, among others: the semiconductor industry in general and the foundry industry in particular; demand for our services and products; our financial condition and results of operations; our plans for expansion; technological and other product developments; the securities markets in Taiwan and elsewhere; and the performance of our equity securities on the Taiwan Stock Exchange and the New York Stock Exchange. The provision of this information should not be interpreted as indicating that it currently should be relied upon in any respect for making investment decisions.

Certain documents and information that we are providing on our website contain statements that are “forward looking statements” within the meaning of Section 27A of the United States Securities Act of 1933, as amended, and Section 21E of the United States Securities Exchange Act of 1934, as amended. These forward-looking statements include, but are not limited to, statements regarding projected revenues, expenses and other financial performance measures, technology mixes, capacity, utilization or loading rates, manufacturing capability and process and geographical diversification. These forward looking statements are made based on our management’s forecasts, expectations, assumptions, judgements and beliefs at the time of such statements. Such forward-looking statements are subject to a number of known and unknown risks and uncertainties that can cause actual results to differ materially from those expressed or implied by such statements, including but are not limited to, risks related to the semiconductor industry, the foundry marketplace, acceptance and demand for products, technological and development risks, competitive factors, global and regional regulatory environment and other risks, including risk factors stated in the section entitled “Item 3. Key Information–D. Risk Factors” in our Annual Report on Form 20-F filed with the United States Securities and Exchange Commission (“SEC”) and other filings with the SEC. Moreover, certain of the financial information was prepared and published in accordance with requirements of the Republic of China Securities and Futures Bureau and is presented in conformity with accounting principles generally accepted in the Republic of China. Readers are cautioned that these accounting principles differ in a number of respects from accounting principles generally accepted in the United States of America.

Our release of financial forecasts and forward-looking statements at any particular time does not create any duty of disclosure beyond that which is imposed by law, and we expressly disclaim any duty to update these forecasts and forward-looking statements for events or circumstances that occur subsequent to such time.
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